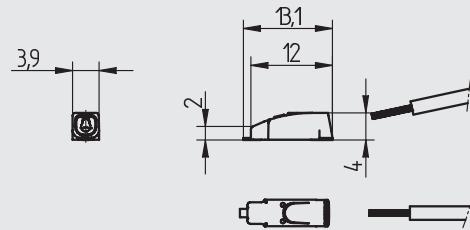


SMD-Terminal block - Mini



pkg. wt. part no.
1800 0,25 g 46.101.1001.50

SMD-Terminal block - Mini with push wire contacts**1 pole**

Direct insertion of solid and stranded, tinned wire ends

Wires can be released by twisting and pulling the wire simultaneously.

Mounting and wiring position: PCB top side

Machine-compatible "tape-and-reel" packaging

Fixing: Lead-free reflow soldering according to DIN EN 610760-1, section 6

Material: Housing: PPA, white

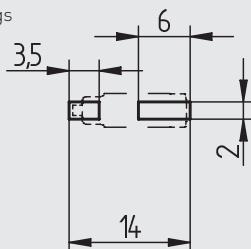
Clamping spring material: CrNi

Contact material: CuSn

Contact surface: hot-dip tinned 5-10 µm

General note: It is recommended to make an electrical connection between both poles of each polarity on the solder pad.

Recommended dimensions
for solder tags



LED LINE	U _{imp} 2,5 kV				CAD
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Connection data	
Connection technology	Push wire contacts
Solid wires	0.34 - 0.75 mm ² , AWG 22-18
Stranded, tinned wires	0.34 - 0.5 mm ² , AWG 22-20
Strip length	8 ± 1 mm
Conductor entry angle to the PCB	0 - 12°
Wire release function by	Twisting and Pulling

Pull-out force according to DIN 60999-1	
0.2 mm ²	min. 10 N
0.34 mm ²	min. 15 N
0.5 mm ²	min. 20 N
0.75 mm ²	min. 30 N
Insertion force	max. 10 N

Geometrical data	
Pin spacing	4 mm / 0.16 inch
Width	3.9 mm / 0.15 inch
Height	4 mm / 0.16 inch
Depth	13.1 mm / 0.52 inch
Reel diameter of tape-and-reel packaging	330 mm (13")
Reel width	24 mm
Pitch distance	8 mm
Packaging unit tape-and-reel	1.500 / 1.800
Packaging unit cardboard	21.600 / 23.400 (13 reels)

Material data	
Insulating material group	I
Insulating material	PPA, white
PTI	600
Flammability class, based on UL 94	V0
Clamping spring material	CrNi
Contact material	CuSn
Contact surface	hot-dipped tinned 5-10 µm

Mechanical data	
Mounting position	PCB top side
Mounting type	Lead-free reflow soldering

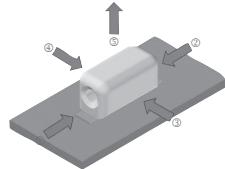
Temperature data	
Marginal temperatures	-40 °C to + 150 °C
Ambient temperature	-40 °C to + 105 °C
T-classification according to IEC 60998-1 para. 12	-

Rated data according to IEC / EN 60947-7-4 (IEC/EN 60664-1)	
Rated voltage (III / 3)	63 V
Rated impulse voltage (III / 3)	2.5 kV
Rated voltage (III / 2)	160 V
Rated impulse voltage (III / 2)	2.5 kV
Rated voltage (II / 2)	320 V
Rated impulse voltage (II / 2)	2.5 kV
Rated current	9 A

Rated data according to UL 1977	
Rated voltage UL 1977	300 V
Rated current UL 1977	9 A

Country specific certificates	
VDE ENEC	EN 60947
UL	cURus, File No. E-365006

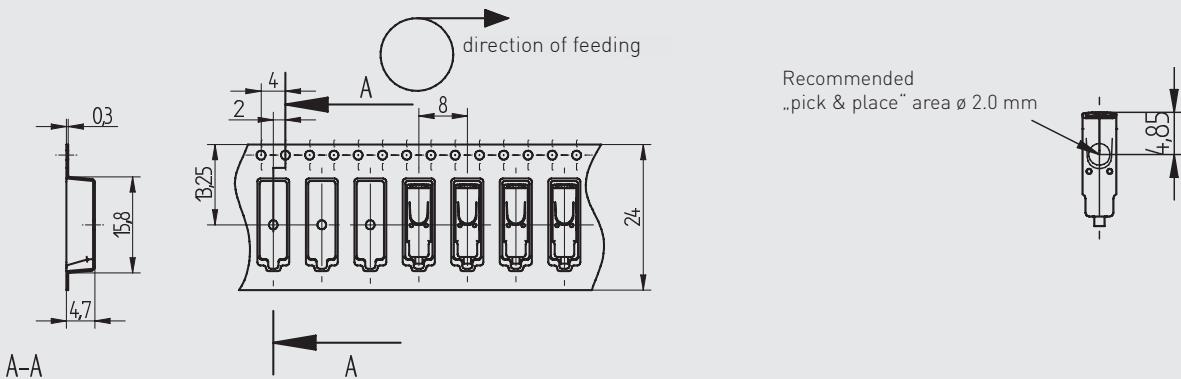
Shear forces according to DIN 6137-1-2 in [N]	
Direction 1 + 2 shear force along	>50
Direction 3 + 4 shear force across	>20
Direction 5 pull-off force	>20

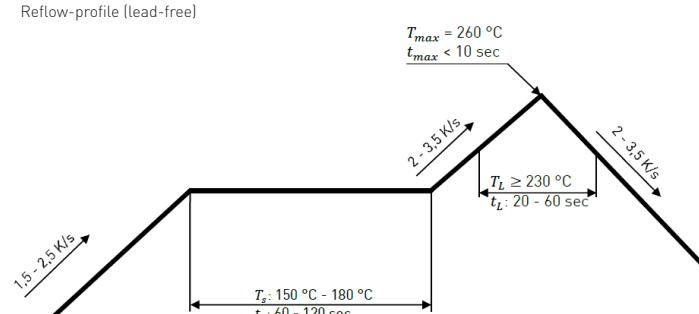


Instructions for soldering process

Suitable for leadfree-reflow-profiles according to DIN EN 61760-1 respective DIN EN 60068-2-58 up to peak-temperature of max. 260°C. Due to different application-specific parameters (component arrangement and alignment, soldering system, solder paste), it is recommended to use test runs to determine a suitable profile under production conditions.

Depending on the SMD soldering process and associated parameters a minor discoloration might occur. However, this will not influence the functionality.



Storage time	Solderability up to 6 months when stored between -5°C and +40°C and rel. humidity between 10...60% r H. After a storage time of 6 months, solderability has to be checked according to J-STD-002D or DIN EN 60068-2-58:2016.
max. allowed number of reflow-processes	3
Reflow-profile	Reflow-profile (lead-free) 
Solderability	Solderability of components is checked by wetting test according to J-STD-002D
Assembly method	SMD, according to drawing
Recommended solder stencil thickness	100 - 150 µm (recommendation BJB 150)